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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
10/710,400	07/08/2004	Min-Lung Huang	11569-US-PA 4399	
31561	7590 03/23/2005		EXAMINER	
JIANQ CHYUN INTELLECTUAL PROPERTY OFFICE			FARAHANI, DANA	
7 FLOOR-1, NO. 100 ROOSEVELT ROAD, SECTION 2		ART UNIT	PAPER NUMBER	
TAIPEI, 100			2891	
TAIWAN			DATE MAILED: 03/23/2005	5

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)				
	10 / 710,400 .	HUANG, MIN-LUNG				
Office Action Summary	Examiner	Art Unit				
•	Dana Farahani	2829				
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the co	orrespondence address				
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply If NO period for reply is specified above, the maximum statutory period we failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	66(a). In no event, however, may a reply be time within the statutory minimum of thirty (30) days fill apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	ely filed s will be considered timely. the mailing date of this communication. O (35 U.S.C. § 133).				
Status						
1)⊠ Responsive to communication(s) filed on <i>08 July 2004</i> .						
2a) ☐ This action is FINAL. 2b) ☒ This	This action is FINAL. 2b)⊠ This action is non-final.					
3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is						
closed in accordance with the practice under E	closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims						
4)⊠ Claim(s) <u>1-15</u> is/are pending in the application.						
4a) Of the above claim(s) is/are withdrawn from consideration.						
5) Claim(s) is/are allowed.						
6)⊠ Claim(s) <u>1-15</u> is/are rejected.)⊠ Claim(s) <u>1-15</u> is/are rejected.					
7) Claim(s) is/are objected to.						
8) Claim(s) are subject to restriction and/or	r election requirement.					
Application Papers						
9) The specification is objected to by the Examine	r.					
10) ☐ The drawing(s) filed on is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.						
Applicant may not request that any objection to the						
Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Ex						
Priority under 35 U.S.C. § 119						
12) ☐ Acknowledgment is made of a claim for foreign a) ☐ All b) ☐ Some * c) ☐ None of:	priority under 35 U.S.C. § 119(a))-(d) or (f).				
1. Certified copies of the priority documents have been received.						
2. Certified copies of the priority documents have been received in Application No						
3. Copies of the certified copies of the prior		ed in this National Stage				
application from the International Bureau	•					
* See the attached detailed Office action for a list	or the certified copies not receive	ea.				
Attachment(s)						
1) Notice of References Cited (PTO-892)	4) Interview Summary					
 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date 	Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:	Patent Application (PTO-152)				

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DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

The changes made to 35 U.S.C. 102(e) by the American Inventors Protection Act of 1999 (AIPA) and the Intellectual Property and High Technology Technical Amendments Act of 2002 do not apply when the reference is a U.S. patent resulting directly or indirectly from an international application filed before November 29, 2000. Therefore, the prior art date of the reference is determined under 35 U.S.C. 102(e) prior to the amendment by the AIPA (pre-AIPA 35 U.S.C. 102(e)).

2. Claims 1-10 are rejected under 35 U.S.C. 102(e) as being anticipated by Morken et al., hereinafter Morken (US Patent 6,657,707).

Regarding claim 1, Morken discloses in figure 1, a bonding pad structure suitable for use in a chip 1, the chip having an active surface S, the bonding pad structure comprising a bonding pad 6 disposed on the active surface; and a protruding pad 7, disposed on the bonding pad and protruded from a top surface of the bonding pad, a turning angle existing at a bonding location between a side profile of the protruding pad and a top surface of the bonding pad, as can be seen in the figure, wherein the turning

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angle is less than 90 degrees for smoothing a current turning path when a current flows through the turning angle.

Regarding claims 2 and 7, the side profile of the protruding pad is a curving surface, as can be seen in the figure.

Regarding claims 3 and 8, the side profile of the protruding pad is an arc surface, as can be seen in the figure.

Regarding claim 4, the material of the protruding pad is copper (see column 2, line 28).

Regarding claims 6 and 10, Morken discloses a conductive bump 8, and that a UBM gold layer can be formed on the surface of the protruding layer 7 (see column 2, lines 31-34).

Claim Rejections - 35 USC § 103

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 4. Claim 11 is rejected under 35 U.S.C. 103(a) as being unpatentable over Morken.

Morken substantially discloses the limitations in the claims, as discussed above, except for the turning angle is less than 45 degrees. However, it would have been

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obvious to one of ordinary skill in the art at the time of the invention to make the turning angle with a specific value in order to adjust the conductivity characteristics of the structure. See <u>In re Woodruff</u>, 919 F.2d 1575, 1578, 16 USPQ2d 1934, 1936 (Fed. Cir. 1990) for the proposition that Where patentability is said to be based upon particular chosen dimensions or upon another variable recited in a claim, the Applicant must show that the chosen dimensions are critical.

5. Claim 12 is rejected under 35 U.S.C. 103(a) as being unpatentable over Morken, as applied to claim 6 above, and further in view of Applicant's Admitted Prior Art (AAPA).

Morken substantially discloses the limitations in the claims, as discussed above, except for disclosing the conductive bump layer includes alloy of tin and lead.

AAPA discloses in figure 1 and paragraph 8, that the bump 122 can be a tin-lead alloy. Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention to use a tin-lead alloy as the bump of the Morken to take advantage of the conductive properties of the alloy.

6. Claims 13-15 are rejected under 35 U.S.C. 103(a) as being unpatentable over Morken in view of AAPA.

Morken substantially discloses the limitations in the claims, as discussed above, except for a passivation layer on the active surface.

AAPA discloses in figure 1, a passivation layer 104 on the active surface of the chip 100. Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention to use a passivation layer on the active surface of the Morken

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structure in order to protect the active surface from environmental hazards such as moisture.

Regarding claim 14, in the Morken reference, the side profile of the protruding pad is a curving surface, as can be seen in the figure.

Regarding claim 15, in the Morken reference, the side profile of the protruding pad is an arc surface, as can be seen in the figure.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Dana Farahani whose telephone number is (571)272-1706. The examiner can normally be reached on M-F 9:00AM - 6:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Bill Baumeister can be reached on (571)272-1722. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

D. Farahani

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